

SEMICONDUCTOR PACKAGES AND METHODS FOR MAKING THE SAME**Abstract of the Invention**

Semiconductor package support elements including cover members
5 attached to one or more reject die sites are provided. Methods for making the
support elements of the present invention and for making semiconductor
packages using the same are also provided. Reject die sites on defective
substrates of a support element are covered prior to the encapsulation process
using a cover member. The cover member comprises, for example, pressure-
10 sensitive or temperature-activated tape, reject dies, or the like. The support
elements and methods of the present invention virtually eliminate bleeding or
flashing during encapsulation due to the presence of reject die sites. The
support elements and methods of the present invention further ensure that
functional dice are not sacrificed by being attached to reject die sites, thereby
15 decreasing manufacturing costs while increasing yield of functional
semiconductor packages.